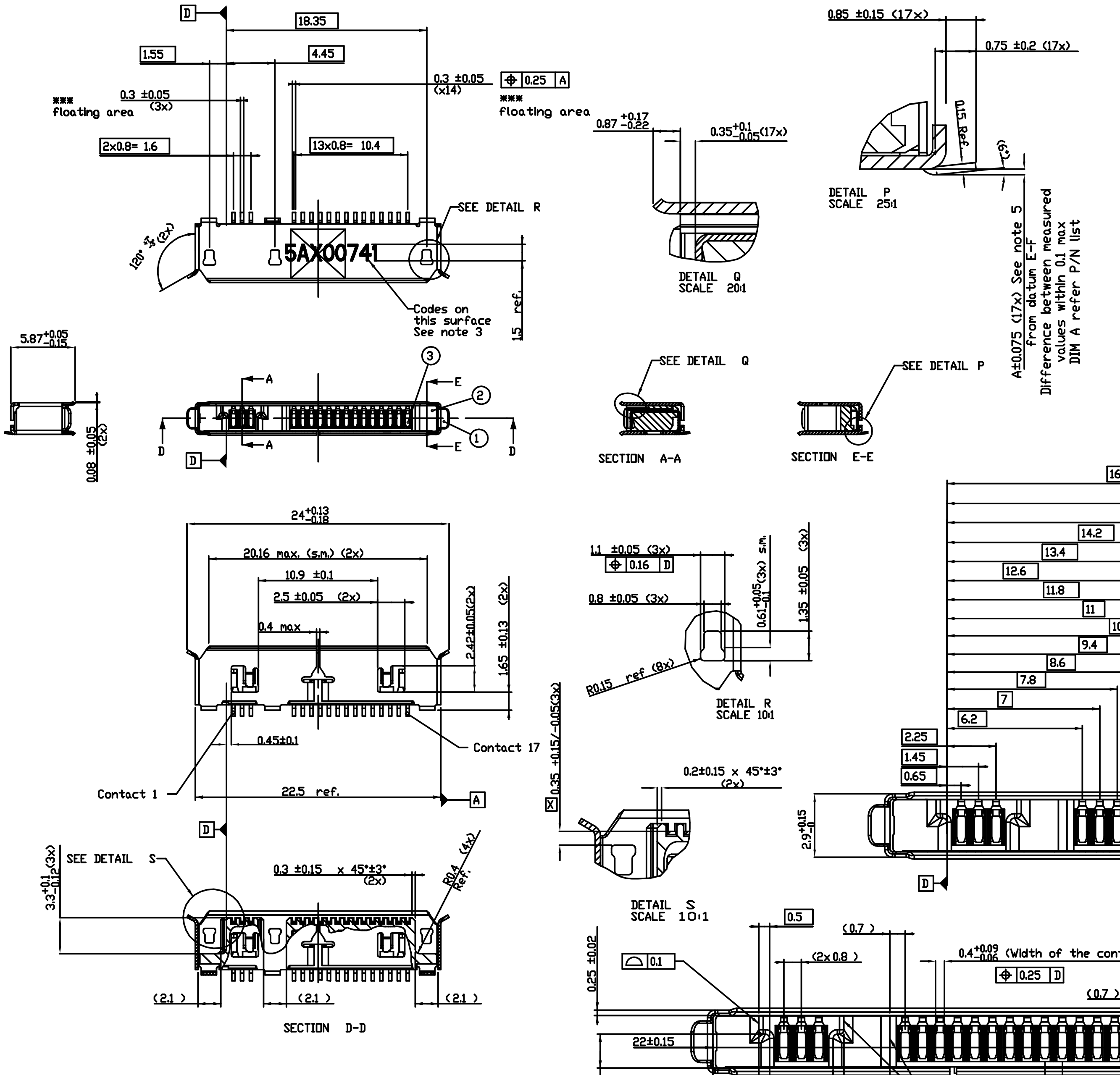
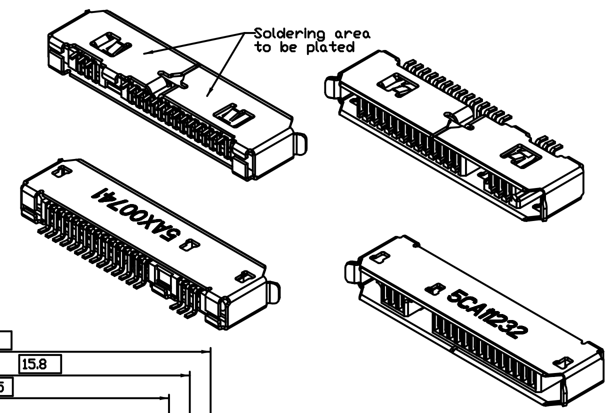
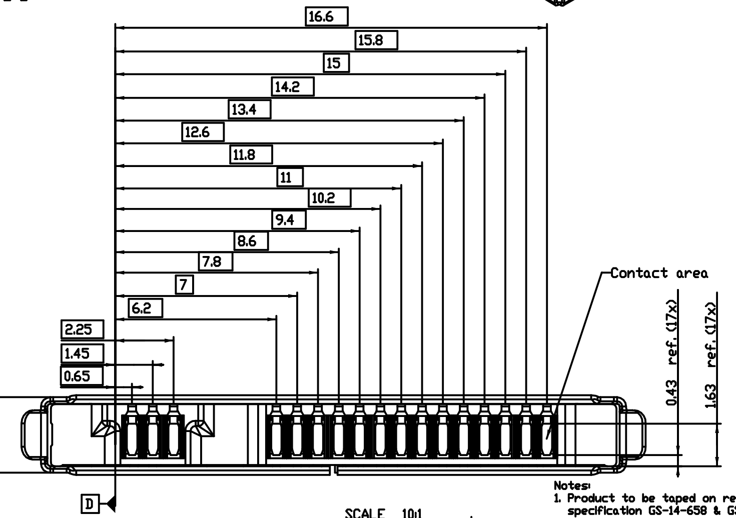
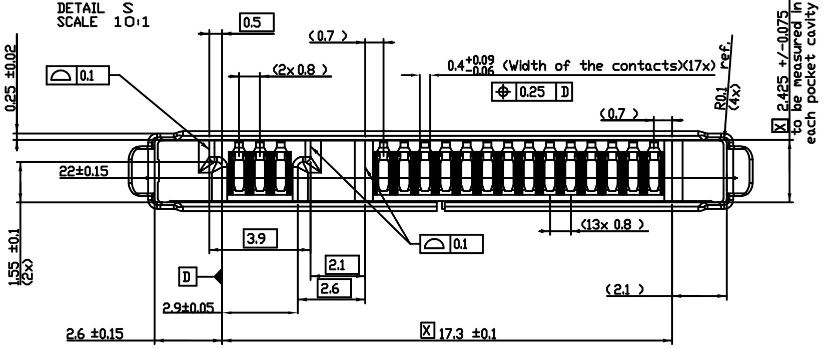
Item	Description	Material	Plating
1	Shield	Stainless steel Thickness 0.25±0.02	1,27um min Nickel underplating 2~5um min SnPb for 63600-301 on soldering area only or 2~5um min Pure Sn for 63600-301LF/502LF on soldering area only
2	Housing	Liquid Cristal Polymer colour black	
3	Contact	Phosphorbronze Thickness 0.15±0.01	0.6um min Nickel underpalting in solder tail and 1.27um min Nickel underplating in gold contact side. Followed by 0.8um min Palladium Nickel with 0.08um gold flash in gold contact side. 3~5um Pure Sn for 63600-301LF/502LF or 3~5um SnPb for 63600-301 in solder tail except cut-off area at the end of solder tails.









FCI P/N	Motorola P/N	DIM A
63600-301	0987636K05	0.025
63600-301LF	0988794Y01	0.025
63600-502LF	0988794Y02	0.075

Notes:

1. Product to be taped on reel packaged per packaging specification GS-14-658 & GS-14-920, 1000 pcs product per reel. See sheet 3.
2. See sheet 2 for recommended PCB.
3. Date Code printed on the surface of shield:
   - First digit of date code stands for last digit of Motorola P/N
   - The second digit of date code stands for supply code. FCI is ' A ' character
   - The third character of date code stands for Motorola drawing revision. Now it is ' o ' character.
   - the fourth digit of date code stands for last digit of year
   - the fifth, sixth, seventh digits of date code stand for day number(3 digits)
   - last digit of date code stands for shift number
4. Critical dimension
5. Measurement method for coplanaruty, true position and bow according to document QC10200
6. s.m. : sharp measurement
7. The housing will withstand exposure to 260°C peak temperature for 10 seconds in a convection, infra red vapor phase reflow oven
8. 63600-301LF&502LF meets European union directives and other country regulations as described in GS-22-008

ltr	ecn no	dr	date			
F	H00355	JGI	001018	linear	.X±0.20	
G	H10250	SCL	010710		.XX±0.10	
H	LS2082	SCL	020828	angles		
J	DG04-0075	PM	041028	dr	J.Gibbels	991013
K	DG04-0089	PM	041201	engr	H.Vereijken	991013
M	DG05-0060	PM	050325	chr	M.Klein	000118
N	DG05-0061	PM	050412	appd	R.Semmeling	000118

mat'l. code: See table

tolerances unless otherwise specified

CUSTOMER COPY

FCI www.fciconnect.com

projection — mm — scale 5:1

title: IN-PHONE 17 pos. Connector Assy

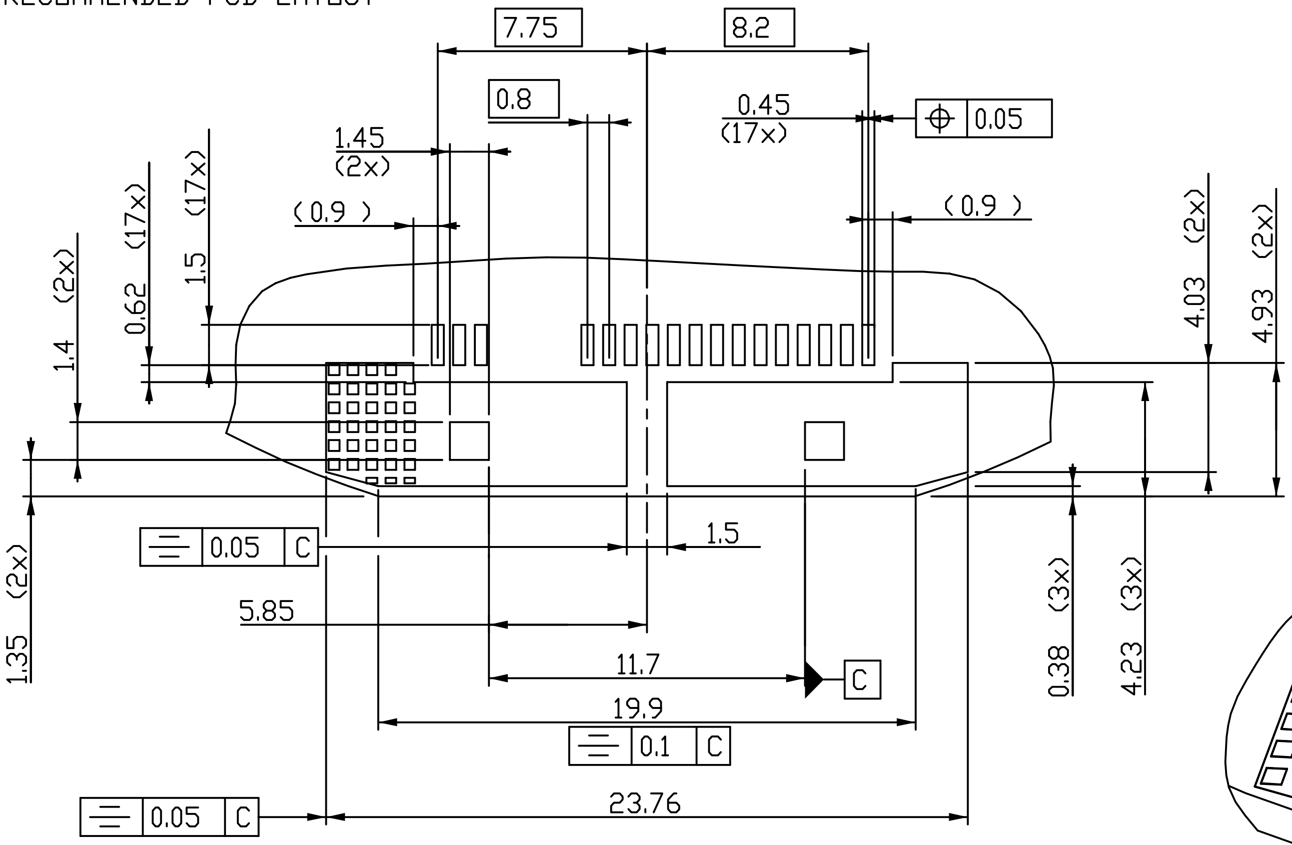
product family: Mobile I/O — code: 213

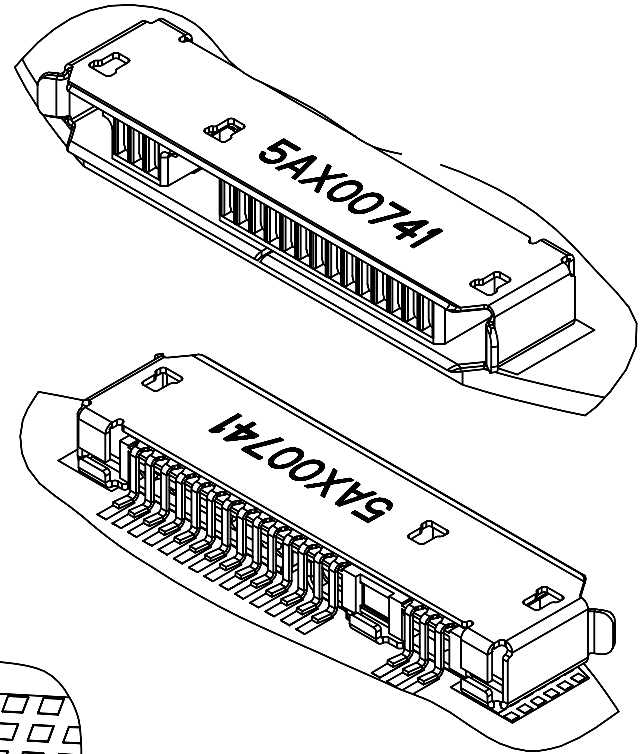
size: A1 — dwg no: 63600 — sheet: 1 of 3

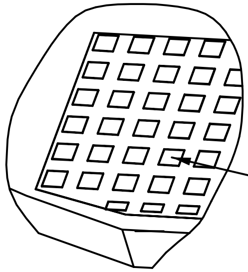
sheet index / revision: N L M

PDM: Rev:N   STATUS: Released   Printed: May 16, 2006

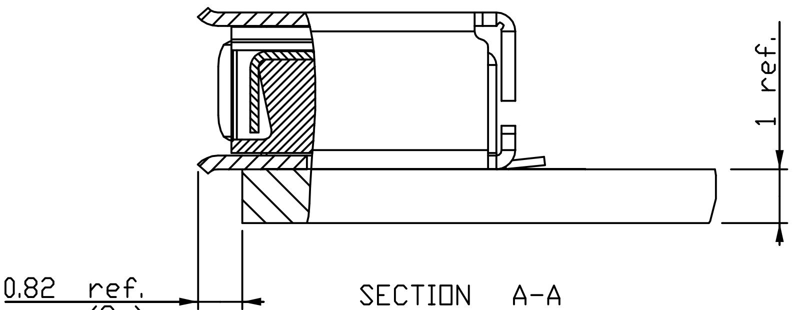
RECOMMENDED PCB LAYOUT







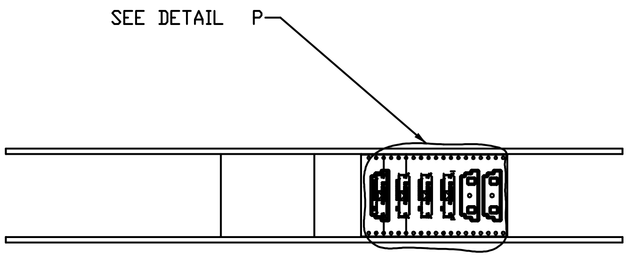
recommended solder paste layout

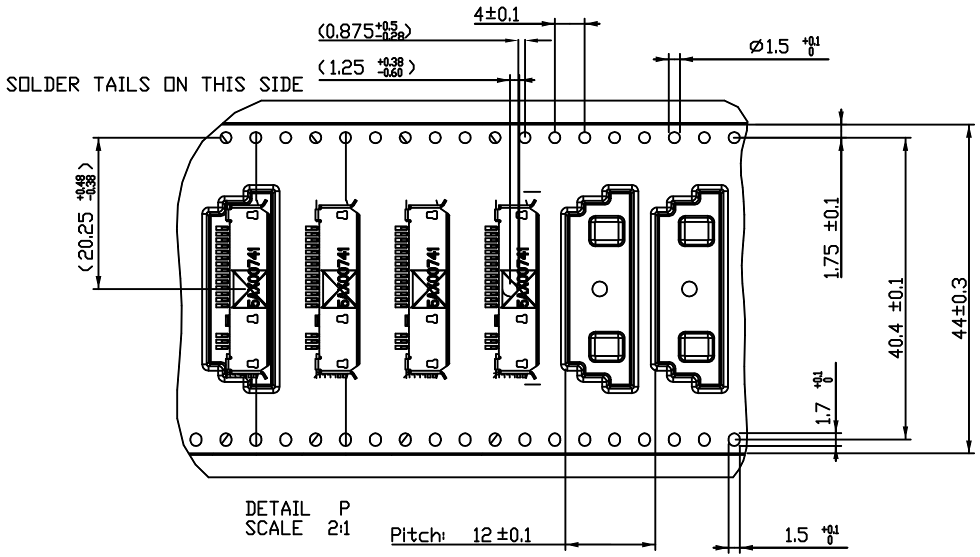


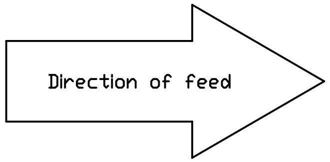
SECTION A-A
SCALE 10:1

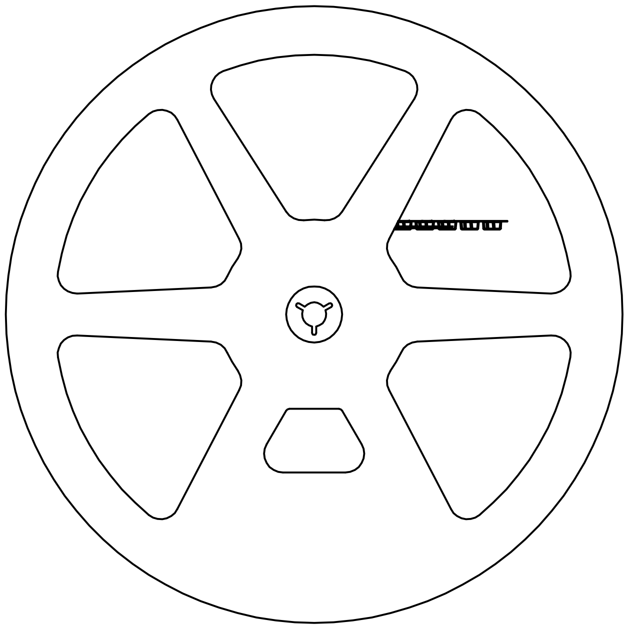
mat'l. code See table	tolerances unless otherwise specified	CUSTOMER COPY	FCI www.fciconnect.com
ltr: L	linear / angles	projection	title: IN-PHONE 17 pos. Connector Assy
	dr J.Gibbels 991013	mm	product family: Mobile I/O; code: 213
	engr H.Vereijken 991013		size: A1; dwg no: 63600
	chr M.Klein 000118	scale 5:1	sheet: 2 of
	appd R.Semmeling 000118		

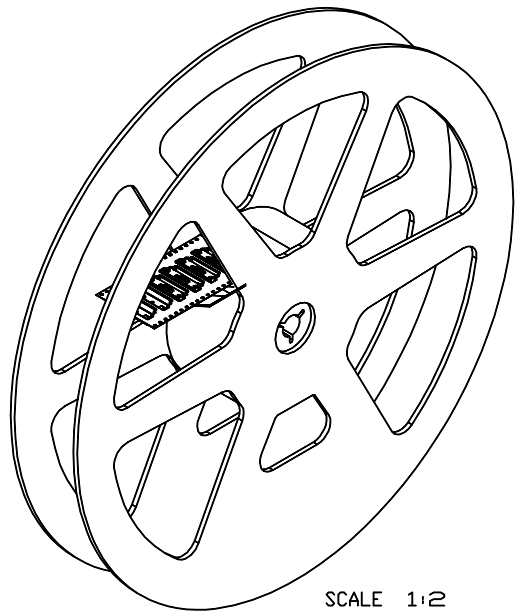
PDM: Rev:N STATUS: Released Printed: May 16, 2006











Notes:

1. "LF" suffix of P/N means lead free product
   a. The housing will withstand exposure to 260° C peak temperature for 10 seconds in a convection, infra red vapor phase reflow oven
   b. This product meets European union directives and other country regulations as described in GS-22-008

THIS FILE WAS ORIGINALLY CREATED IN THE PRO ENGINEER ENVIRONMENT AND ANY FUTURE REVISIONS TO THIS FILE MUST BE MADE IN THE PRO ENGINEER ENVIRONMENT

mat'l. code: See table	tolerances unless otherwise specified	CUSTOMER COPY	FCI www.fciconnect.com
ltr: M	linear / angles	projection	title: IN-PHONE 17 pos. Connector Assy
	dr: J.Gibbels 991013	mm	product family: Mobile I/O; code: 213
	engr: H.Vereijken 991013		size: A1; dwg no: 63600
	chr: M.Klein 000118	scale: 5:1	sheet: 3 of
	appd: R.Semmeling 000118		

PDM: Rev:N STATUS: Released Printed: May 16, 2006